- Inputs Are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes
 PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC[™] (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

These devices contain a single 8-input NAND gate and perform the following Boolean functions in positive logic:

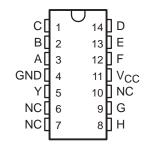
$$Y = \overline{A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H}$$
 or $Y = \overline{A + B + C + D + E + F + G + H}$

The 54ACT11030 is characterized for operation over the full military temperature range of -55°C to 125°C. The 74ACT11030 is characterized for operation from -40°C to 85°C.

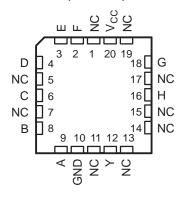
FUNCTION TABLE

INPUTS A THRU H	OUTPUT Y
All inputs H	L
One or more inputs L	Н

54ACT11030 . . . J PACKAGE 74ACT11030 . . . D OR N PACKAGE (TOP VIEW)

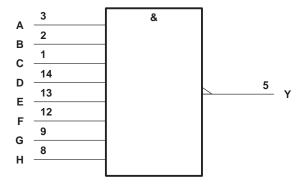


54ACT11030 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

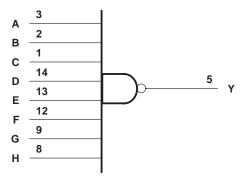
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



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54ACT11030, 74ACT11030 8-INPUT POSITIVE-NAND GATES

SCLS050 - MARCH 1987 - REVISED APRIL 1993

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input voltage range, V _I (see Note 1)	V to V_{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	V to V_{CC} + 0.5 V
Input clamp current, $I_{ K }$ ($V_{ }$ < 0 or $V_{ }$ > V_{CC})	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions

		54ACT11030		74ACT	UNIT	
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	V
ІОН	High-level output current		-24		-24	mA
l _{OL}	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	T,	д = 25°C	;	54ACT	11030	74ACT	UNIT	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	I _{OH} = – 50 μA	4.5 V	4.4			4.4		4.4		
	ΙΟΗ = – 50 μΑ	5.5 V	5.4			5.4		5.4		
\/a	IOH = -24 mA	4.5 V	3.94			3.7		3.8		V
VOH	10H = -24 IIIA	5.5 V	4.94			4.7		4.8		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
	ΙΟΣ = 30 μΑ	5.5 V			0.1		0.1		0.1	
\/a:	lo 24 mA	4.5 V			0.36		0.5		0.44	V
VOL	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44	V
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		80		40	μΑ
∆l _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
Ci	$V_I = V_{CC}$ or GND	5 V		3.5						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

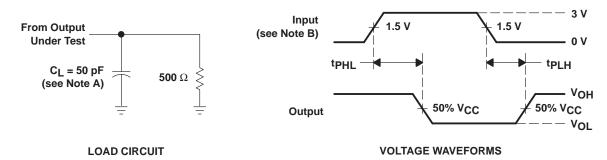
PARAMETER	FROM	то	T,	Δ = 25°C	;	54ACT	11030	74ACT	11030	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A thru H	V	1.5	5.4	8.1	1.5	8.8	1.5	8.5	
^t PHL	A tillu fi	ſ	1.5	5.9	7.8	1.5	9.3	1.5	8.7	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per gate	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	41	pF

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- C. The outputs are measured one at a time with one input transition per measurement.

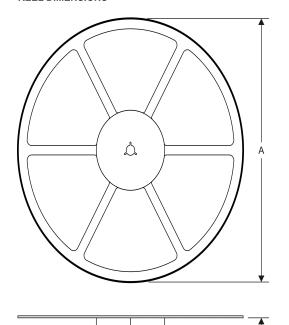
Figure 1. Load Circuit and Voltage Waveforms

PACKAGE MATERIALS INFORMATION

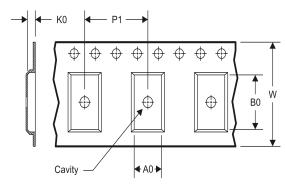
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT11030DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

	Device Package Type		Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
I	74ACT11030DR	SOIC	D	14	2500	367.0	367.0	38.0	

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